

STOD14

700 mA dual DC-DC converter for powering AMOLED displays

Datasheet — production data

Features

- Step-down and inverter converters
- Operating input voltage range from 6 V to 13 V
- Synchronous rectification for both converters
- 700 mA output current
- Fixed positive voltage 4.6 V
- Programmable negative voltage by S_{WIRE} from - 2.4 V to - 6.0 V
- Typical efficiency 85%
- PWM mode controller @ 1.6 MHz switching frequency
- Enable pin for shutdown mode
- Low quiescent current in shutdown mode
- Soft-start with inrush current protection
- Short-circuit protection on positive output
- Overtemperature protection
- Temperature range 40 °C to 85 °C
- True shutdown mode
- Fast output discharge after shutdown
- Package DFN 4x4 mm 12 leads 0.75 mm height, 0.5 mm pitch

Applications

- Digital photo frames
- Ultra mobile PCs
- Mobile Internet devices
- Digital still cameras / camcorders
- Portable media players / DVD players

Device summarv



Description

The STOD14 is a dual channel DC-DC converter driver for medium-sized AMOLED display panels. It integrates a step-down and an inverting converter in a compact IC design. The excellent efficiency makes it particularly suitable for battery operated products. The high frequency operation allows the value and size of external components to be reduced.

The positive output voltage is fixed at 4.6 V with very high current capability and is generated using a buck converter. The negative output is programmable by an external MCU through a dedicated pin which implements single-wire protocol, with values from - 2.4 to - 6.0 V.

Soft-start with controlled inrush current limit, load disconnect and thermal shutdown are integrated functions of the device.

Order code	Positive voltage	Negative voltage	Package	Packaging
STOD14PUR	4.6 V	- 2.4 V to - 6.0 V	DFN12L (4 x 4 mm)	3000 parts per reel

Table 1.

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This is information on a product in full production.

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1 Schematic



Figure 1. Application schematic

Table 2. Typical external components

Description	Manufacturer Part number Value		Size	Ratings	
L ₁	Coilcraft	LPS4012-472MLB	4.7 µH	4 x 4 x 1.2	1.6 A / 1.8 A ⁽¹⁾
L ₂	Coilcraft	LPS4012-472MLB	4.7 µH	4 x 4 x 1.2	1.6 A / 1.8 A ⁽¹⁾
C _{INA}	Murata	GRM21BR61C106KE15L	10 µF	0805	X5R, 16 V
C _{INP}	Murata	2x GRM21BR61C106KE15L	2x 10 µF ⁽²⁾	0805	X5R, 16 V
C _{O1}	Murata	2x GRM21BR61C106KE15L	2x 10 µF	0805	X5R, 16 V
C _{O2}	Murata	2x GRM21BR61C106KE15L	2x 10 µF	0805	X5R, 16 V
C _{REF}	Murata	GRM185R60J105KE26D	1.0 µF	0603	X5R, 6.3 V

1. $~I_{SAT}$ 10% drop / 30% drop.

2. Doubled C_{INP} useful at low temperatures.

Note: All the above components refer to the typical application performance characteristics. Operation of the device is not limited to the choice of these external components.





Figure 2. Block schematic



STOD14

2 Pin configuration

Figure 3. Pin configuration (top view)



Table 3. Pin description

Symbol	Pin	Description
V _{O2}	1	Inverting converter output voltage (negative)
LX2	2	Switching node of the inverting converter
V _{inIV}	3	Power input supply voltage for inverting converter
V _{inBK}	4	Power input supply voltage for step-down converter
LX1	5	Switching node of the step-down converter
PGND	6	Power ground pin
V _{O1}	7	Step-down converter output voltage (positive)
AGND	8	Signal ground pin. This pin must be connected to power ground pin
S _{WIRE}	9	S- _{WIRE} pin
V _{inA}	10	Analog input supply voltage
EN	11	Enable control pin. ON = HIGH. When pulled low, puts the device into shutdown mode
V _{REF}	12	Voltage reference output. Connect 1 μF bypass capacitor between this pin and AGND
EXPOS	ED PAD	Exposed pad must be connected to AGND and PGND in the PCB layout in order to guarantee proper operation of the device.

3 Maximum ratings

Table 4.	Absolute maximum ratings						
Symbol	Parameter	Value	Unit				
VinA, VinIV, VinBK	DC supply voltage	- 0.3 to 13.5	V				
EN, S _{WIRE}	Enable pin, S- _{WIRE} pin	- 0.3 to 4.6	V				
ILx2	Inverting converter switching current	Internally limited	А				
Lx2	Inverting converter switching node	- 6.5 to VINP +0.3	V				
VO2	Inverting converter output voltage	- 6.0 to GND +0.3	V				
VO1	Step-down converter output voltage	- 0.3 to 6	V				
Lx1	Step-down converter switching node	- 0.3 to VINP +0.3	V				
ILx1	Step-down converter switching current	Internally limited	А				
VREF	Reference voltage	- 0.3 to 3	V				
PD	Power dissipation	Internally limited	mW				
T _{STG}	Storage temperature range	- 65 to 150	°C				
Т _Ј	Maximum junction temperature	150	°C				
ESD	Human body model ESD protection	2	kV				

Table 4. Absolute maximum ratings

Note: Absolute maximum ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied.

Table 5. Thermal data

Symbol	Parameter	Value	Unit
R _{thJA}	Thermal resistance junction-ambient (1)	33	°C/W
R _{thJC}	Thermal resistance junction-case (FR-4 PCB)	1.64	°C/W

1. The package is mounted on a 4-layer (2S2P) JEDEC board as per JESD51-7 and JESD51-5.



4 Electrical characteristics

 $T_{A} = 25 \ ^{\circ}C, \ V_{INA} = V_{INP} = 9.0 \ V, \ I_{O1,2} = 150 \ mA, \ C_{IN} = 10 \ \mu\text{F}, \ C_{O1,2} = 22 \ \mu\text{F}, \ C_{REF} = 1 \ \mu\text{F}, \\ L1 = 4.7 \ \mu\text{H}, \ L2 = 4.7 \ \mu\text{H}, \ V_{EN} = \text{High}, \ V_{O1} = 4.6 \ V, \ V_{O2} = - 4.9 \ V, \ \text{unless otherwise specified.}$

Symbol V _{IN}	Parameter	Test conditions				
V _{IN}		Min.	Тур.	Max.	Unit	
	Operating input voltage range	$T_A = -40$ to 85 °C	6		13	V
UVLO_H	Undervoltage lockout HIGH	V_{INA} rising, T_A = -40 to 85 °C		5	5.2	V
UVLO_L	Undervoltage lockout LOW	V_{INA} falling, $T_A = -40$ to 85 °C	4.6	4.8		V
I_VI	Input current	No load condition $(I_V_I = I_{INA} + I_{INP})$		30		mA
I _{Q_SH}	Shutdown current	$V_{EN} = GND$, $(I_{Q_SH} = I_{INA} + I_{INP})$			5	μA
V _{EN} H	Enable HIGH threshold	$V_{INA} = 6$ V to 13 V, $T_A = -40$ to 85 °C	1.2			V
V _{EN} L	Enable LOW threshold	$V_{INA} = 6$ V to 13 V, $T_A = -40$ to 85 °C			0.4	V
I _{EN}	Enable input current	$V_{EN} = V_{IN}$			1	μA
F _{SW}	Frequency	PWM mode, T _A = -40 to 85 °C	1.44	1.6	1.76	MHz
D1 _{MAX}	Step-down maximum duty cycle	No load	load			
D2 _{MAX}	Inverting maximum duty cycle	No load	90			%
		$I_{O1,2} = 10 \text{ to } 150 \text{ mA}$ $V_{O1} = 4.6 \text{ V}, V_{O2} = -4.9 \text{ V}$	see figure			%
η	Total system efficiency	I _{O1,2} =150 to 700 mA V _{O1} =4.6 V, V _{O2} =-4.9 V		85		%
V _{REF}	Voltage reference	I _{REF} = 10 μA	1.198	1.211	1.222	V
I _{REF}	Voltage reference current capability	At V _{REF} = V _{REF} - 1.5%	100			μA
tep-down c	converter section			1		
V _{O1}	Output voltage	V_{INA} =6 V to 13 V, I_{O1} =5 mA to 700 mA, T_A =-40 °C to 85 °C	4.55	4.6	4.65	v
		$V_{INA}{=}6$ V to 13 V, $I_{O1}{=}5$ mA I_{O2} no load; $T_{A}{=}{-}40~^\circ\mathrm{C}$ to 85 $^\circ\mathrm{C}$		0.5		
$\Delta V_{O1 SL}$	Static line regulation ⁽¹⁾	$V_{INA}{=}6$ V to 13 V, $I_{O1}{=}700$ mA I_{O2} no load, $T_{A}{=}{-}40~^\circ\mathrm{C}$ to 85 $^\circ\mathrm{C}$		0.5		%
A)/	Static load regulation ⁽²⁾	I_{O1} =5 to 700 mA, I_{O2} no load, V_{INA} =6 V; T_{A} =-40 °C to 85 °C		1		۵/
ΔV_{O1}	Static load regulation (*)	I_{O1} =5 to 700 mA, I_{O2} no load, V_{INA} =13 V; T_A =-40 °C to 85 °C		1		%
I _{O1}	Maximum step-down output current	V _I =6 V to 13 V	700			mA

Table 6. Electrical characteristics

Table 6.	Electrical characteris	tics (continued)				
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I-L _{1MAX}	Inductor peak current	V _{O1} below 10% of nominal value	1.2			Α
R _{DSON} P1		T _A = -40 to 85 °C		0.2	0.5	Ω
R _{DSON} N1		$T_A = -40$ to 85 °C		0.18	0.5	Ω
Inverting co	nverter section	· · · · · ·				
	Output negative voltage range	41 discrete values with 100 mV steps set by $S_{\mbox{WIRE}}$ pin	-6.0		-2.4	V
V _{O2}	Default value	Default output voltage		-4.9		V
	Accuracy	Output voltage variation on the nominal value	-1.4		+1.4	%
A)/	Static line regulation ⁽³⁾	V_{INA} =6 V to 13 V, I_{O2} =5 mA I_{O1} no load; T_A =-40 °C to 85 °C		1		%
$\Delta V_{O2 SL}$		$V_{INA}{=}6$ V to 13 V, $I_{O2}{=}700$ mA I_{O1} no load, $T_{A}{=}{-}40$ °C to 85 °C		1		/0
	Static load regulation ⁽⁴⁾	$ _{O2}=5 \text{ to } 700 \text{ mA}, _{O1} \text{ no load}, V_{INA}=6$ V; T _A =-40 °C to 85 °C		1		%
ΔV_{O2}		I_{O2} =5 to 700 mA, I_{O1} no load, V _{INA} =13 V; T _A =-40 °C to 85 °C		1		70
I _{O2}	Maximum inverting output current	V _{INA} =6 V to 13 V	-700			mA
I-L _{2MAX}	Inductor peak current	V _{O2} below 10% of nominal value			-2.0	Α
R _{DSON} P2		$T_A = -40$ to 85 °C		0.17	0.5	Ω
R _{DSON} N2		$T_A = -40$ to 85 °C		0.16	0.5	Ω
Thermal shu	utdown					
OTP	Overtemperature protection			150		°C
OTP _{HYST}	Overtemperature protection hysteresis			15		°C
Discharge r	esistor					
R _{DIS}	Discharge resistor value			300		Ω
T _{DIS}	Discharge time	No load, from 90% to 10%		15		ms

Table 6.	Electrical characteristics	(continued)

1. [(VO1MAX - VO1MIN) / (VO1 @ 25 °C and VINA, P = 6 V)] x 100.

2. [(VO1MAX - VO1MIN) / (VO1 @ 25 °C and IO1 = 5 mA)] x 100.

3. [(VO2MAX - VO2MIN) / (VO2 @ 25 °C and VINA,P = 6 V)] x 100.

4. [(VO2MAX - VO2MIN) / (VO2 @ 25 °C and IO2 = 5 mA)] x 100.





5 Typical performance characteristics





Figure 6. Fast discharge











Figure 9. Load transient ($t_{\rm R} = 10 \ \mu$ s)Figure 10. Load transient ($t_{\rm F} = 10 \ \mu$ s)Image: Image: Image







f [Hz]	PSRR_VO1 [dB]	PSRR_VO2 [dB]
10	> 60	> 60
100	> 60	> 60
1 000	54	54
2 000	46	48
5 000	40	44
10 000	34	39
20 000	29	35
50 000	31	34
100 000	35	32

6 Application Information

6.1 Inductor selection

The inductor is the key passive component for switching converters.

For the step-down converter an inductance between 3.3 μH and 6.8 μH is recommended. For the inverting stage the suggested inductance ranges from 3.3 μH to 4.7 $\mu H.$

It is very important to select a proper inductor according to the maximum current the inductor can handle in order to avoid saturation. The peak current for the step-down and the inverting can be calculated with the following formulas:

Equation 1

$$I_{PEAK_BUCK} = \frac{V_{O1} \cdot \left(1 - V_{O1} / V_{IN}\right)}{2 \cdot f_s \cdot L_1} + I_O$$

Equation 2

$$I_{\text{PEAK}_INV} = \frac{V_{\text{IN}} \cdot V_{\text{O2}}}{2 \cdot f_{\text{S}} \cdot L_2 (V_{\text{O2}} - V_{\text{IN}})} + \frac{I_{\text{O}} (V_{\text{IN}} - V_{\text{O2}})}{\eta_2 \cdot V_{\text{IN}}}$$

where

 V_{O1} is step-down output voltage

V_{O2} is inverting output voltage including sign

 ${\rm I}_{\rm O}$ is output current for both DC-DC converters

V_{IN} is input voltage; use minimum of operating voltage

 $\rm f_s$ is switching frequency; use the minimum value of 1.44 MHz for worst case

 η_p is inverter efficiency; typ. 85%

L1 is buck inductor value; including tolerance

L2 is inverter inductor value; including tolerance.

6.2 Input and output capacitor selection

It is recommended to use ceramic capacitors with low ESR as input and output capacitors in order to filter any disturbance present in the input line and to get stable operation for the switching converters.

6.3 Recommended PCB layout

The STOD14 is a high frequency power switching device so it requires a proper PCB layout in order to obtain the necessary stability and optimize line/load regulation and output voltage ripple. Analog input (V_{INA}) and power input (V_{INP}) must be kept separated and connected together at the C_{IN} pad only. The input capacitor must be as close as possible to the IC. To minimize the ground noise, a common ground node for power ground and a different one for analog ground must be used. The exposed pad is connected to AGND through vias.

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Figure 12. Top layer and top silkscreen (top view)







7 Detailed description

The STOD14 is a high efficiency dual DC-DC converter which integrates a step-down and inverting power stage suitable for supplying AMOLED panels.

Thanks to the high level of integration it needs only 6 external components to operate and it achieves very high efficiency using a synchronous rectification technique for both the DC-DC converters.

The controller uses an average current mode technique in order to obtain good stability and precise voltage regulation in all possible conditions of input voltage, output voltage and output current. In addition, the peak inductor current is monitored in order to avoid inductor saturation.

The STOD14 avoids battery leakage thanks to the true-shutdown feature and it is self protected from overtemperature. Undervoltage lockout and soft-start guarantee proper operation during startup.

7.1 Mode of operation

To guarantee the minimal output voltage ripple, the device works just in continuous conduction mode (CCM). In this mode, reverse current pulses flowing back to the power supply can appear, especially at low load.

7.2 Enable pin

The device operates when the Enable pin is set high. If the Enable pin is set low, the device stops switching, and all the internal blocks are turned off. In addition, the internal switches are in an OFF state so the load is electrically disconnected from the input. This avoids unwanted current leakage from the input to the load.

When the EN is pulled high, the P1 switch is turned on for 100 μ s. In normal operation, during this time, apart of a small drop due to parasitic resistance, V_{O1} reaches V_{IN}. After 100 μ s, if V_{O1} stays below V_{IN}, the P1 is turned off and stays off until a new pulse is applied to EN. This mechanism avoids the device starting if a short-circuit is present on V_{O1}.

7.3 Soft-start and inrush current limiting

As a first step, the C_{O1} capacitor is charged, the P1 switch implements a current limiting technique in order to keep the charge current below 400 mA. This avoids battery overloading during startup.

After VO1 reaches VINP voltage level, the P1 switch is fully turned on and the soft-start procedure for the step-down is started.

After around 2 ms the soft-start for the inverting is started. The positive and negative voltage is under regulation around 6 ms after the Enable pin is asserted high.

7.4 Startup sequence

After the Enable pin is pulled high, or after a suitable voltage is applied to V_{INP} , V_{INA} and the Enable pin, the device begins the startup phase. The positive and negative voltages are



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under regulation about 10 ms after the Enable pin is asserted high. The short-circuit protection is designed to prevent overload, performing a dynamic current limitation on both output pins. At light load condition (up to 150 mA), the load can be connected during the startup phase. At medium/high load condition (above 150 mA), the proper sequence needs the startup phase to be entirely completed before connecting a load.

7.5 Fast discharge

When the device goes into shutdown mode and LX1 and LX2 stop switching, the discharge switch between V_{O1} and V_{IN} and the switch between V_{O2} and GND turn on and discharge the positive and the negative output voltages. After output voltages are discharged to zero, the switches turn off and the outputs stay in high impedance state.

7.6 Undervoltage lockout

The undervoltage lockout function avoids improper operation of the device when the input voltage is not high enough. When the input voltage is below the UVLO threshold, the device is in shutdown mode. The hysteresis avoids unstable operation at input voltage levels close to the UVLO threshold.

7.7 Overtemperature protection

An internal temperature sensor continuously monitors the IC junction temperature. If the temperature exceeds the specified value (see *Table 5*) the device stops operating. As soon as the temperature falls below the threshold (including hysteresis), normal operation is restored.

7.8 Short-circuit startup detection (SSD)

During device soft-start on positive output, an internal comparator checks load condition to detect eventual panel damage. In such case soft-start is stopped and the device is parked in power-off. To reset the normal functionality (assuming that the anomalous load condition was removed), it is necessary to restart the converter by an enable transient.

If no damage is detected during soft-start on the positive output, the startup procedure follows with negative output soft-start to reach, at the end, normal outputs functionality and voltages.

7.9 Overload protection (OLP)

Output current is internally limited. An overload condition, as a short-circuit between the two outputs or between each output and GND, produces the device power-off. To reset normal functionality (assuming that the short condition was removed), it is necessary to restart the converter by an enable transient.

7.10 Short-circuit protection (SCP)

When short-circuit occurs, the device is able to detect the voltage difference between V_{IN} and V_{OUT} . Overshoots are limited, decreasing the inductor current. After that, the output

stages of the device are turned off. This status is maintained avoiding current flowing to the load. A new enable transition is needed to restart the device. The short-circuit protection is active during startup.

7.11 S-_{WIRE} protocol description

Protocol to digitally communicate over a single cable with single-wire components.

Features and benefits

- Fully digital signal
- No handshake needed
- Protection against glitches and spikes though an internal low-pass filter acting on both rising and falling edges
- Uses a single-wire (plus analog ground) to accomplish both communication and power control transmission
- Simple design with an interface protocol that supplies control and signaling over a single-wire connection to set the output voltages.

S-WIRE protocol

- Single-wire protocol uses conventional CMOS/TTL logic levels (maximum 0.6 V for logic "zero" and a minimum 1.2 V for the logic "one") with operation specified over a supply voltage range of 2.5 V to 4.5 V
- Both master (MCU) and slave (this device) are configured to permit bit sequential data to flow only in one direction at a time; master initiates and controls the device
- Data is bit-sequential with a START bit and a STOP bit
- Signal is transferred in real time
- System clock is not required; each single-wire pulse is self-clocked by the oscillator integrated in the master and asserted valid within a frequency range of 250 kHz (maximum).

S-WIRE basic operations

The negative output voltage levels are selectable within a wide range (steps of 100 mV). The device can be enabled / disabled via S_{WIRE} in combination with the Enable pin.

7.12 Enable and S-_{WIRE} operation

Both S-_{WIRE} and Enable pins can be used to switch on and off the device. *Table 8* describes functionality for all combinations.

EN	S _{WIRE}	Action
Low	Low	Device off
Low	High	Negative output voltage set by S-WIRE
High	Low	Default negative output voltage
High	High	Default negative output voltage

Table 8. EN and S-_{WIRE} operation table



Note: Enable pin must be set to AGND while using the S-_{WIRE} function.

7.13 Programming negative output voltage

Negative output voltage is set through the $S\text{-}_{\rm WIRE}$ interface by providing a number of pulses according to the following table.

Bit clock	V _{O2} (V)								
1	N/A	11	-5.4	21	-4.4	31	-3.4	41	-2.4
2	N/A	12	-5.3	22	-4.3	32	-3.3		
3	N/A	13	-5.2	23	-4.2	33	-3.2		
4	N/A	14	-5.1	24	-4.1	34	-3.1		
5	-6.0	15	-5.0	25	-4.0	35	-3.0		
6	-5.9	16	-4.9	26	-3.9	36	-2.9		
7	-5.8	17	-4.8	27	-3.8	37	-2.8		
8	-5.7	18	-4.7	28	-3.7	38	-2.7		
9	-5.6	19	-4.6	29	-3.6	39	-2.6		
10	-5.5	20	-4.5	30	-3.5	40	-2.5		

 Table 9.
 Negative output voltage programming levels



8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK is an ST trademark.

Dim.	mm				
	Min.	Тур.	Max.		
A	0.70	0.75	0.80		
A1	0	0.02	0.05		
b	0.18	0.25	0.30		
D		4.0			
D2	3.15	3.30	3.40		
E		4.0			
E2	2.50	2.65	2.75		
е		0.5			
L	0.30	0.40	0.50		

Table 10. DFN12L (4 x 4) mechanical data





Figure 14. DFN12L (3 x 3) drawing





Dim.	mm.			inch.		
	Min.	Тур.	Max.	Min.	Тур.	Max.
А			330			12.992
С	12.8		13.2	0.504		0.519
D	20.2			0.795		
Ν	99		101	3.898		3.976
Т			14.4			0.567
Ao		4.35			0.171	
Во		4.35			0.171	
Ko		1.1			0.043	
Po		4			0.157	
Р		8			0.315	

Tape & reel QFNxx/DFNxx (4x4) mechanical data





Figure 15. DFN12L footprint recommended data (dimensions in millimeters)



9 Revision history

Table 11.Document revision history

Date	Revision	Changes
16-Aug-2012	1	Initial release.



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